

Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Withdrawn-Currently Amended) A method of forming a patterned thin-film including a linear portion by frame plating, the method comprising:

~~the step of forming a frame having an undercut near a bottom thereof on a base layer; and~~

~~the plating step of forming the patterned thin-film by plating through the use of the frame such that the linear portion has a first portion and a second portion, wherein the a second portion closeis closer to the base layer than the first portion, and wherein the second portion touches the base layer and hashaving a width greater than a width of the remainingfirst portion of the linear portion.~~

2. (Withdrawn-Currently Amended) The method according to claim 1, wherein the patterned thin-film is formed to include a plurality of linear portions disposed side by side.

3. (Currently Amended) A patterned thin-film disposed on a base layer and including a linear portion, wherein the linear portion has a first portion and a second portion, ~~wherein thea second portion closeis closer~~ to the base layer ~~than the first portion, and wherein the second portion touches the base layer,~~ the second portion having a width greater than a width of the ~~remainingfirst portion of the linear portion.~~

4. (Currently Amended) The patterned thin-film according to claim 3, including a plurality of linear portions disposed side by side.